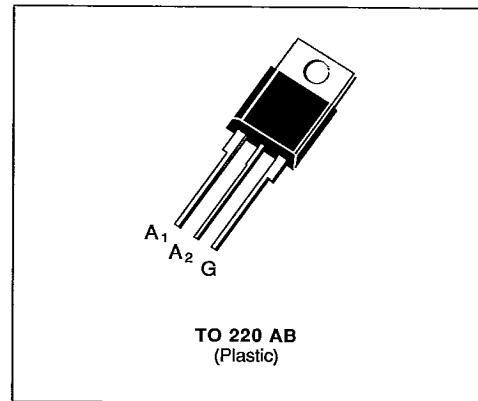


S G S-THOMSON

SENSITIVE GATE TRIACS

- GLASS PASSIVATED CHIP
- I_GT SPECIFIED IN FOUR QUADRANTS
- AVAILABLE IN INSULATED VERSION → BTA SERIES (INSULATING VOLTAGE 2500 V_{RMS}) OR IN UNINSULATED VERSION → BTB SERIES
- UL RECOGNIZED FOR BTA SERIES (E81734)

**DESCRIPTION**

New range suited for applications such as phase control and static switching.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value		Unit
I _{T(RMS)}	RMS on-state Current (360° conduction angle)	T _C = 75 °C	4	A
I _{TSM}	Non Repetitive Surge Peak on-state Current (T _j initial = 25 °C - Half sine wave)	t = 8.3 ms	52	A
		t = 10 ms	50	
I ² t	I ² t Value for Fusing	t = 10 ms	12.5	A ² s
di/dt	Critical Rate of Rise of on-state Current (1)	Repetitive F = 50 Hz	10	A/μs
		Non Repetitive	50	
T _{stg} T _j	Storage and Operating Junction Temperature Range	- 40 to 150 - 40 to 110		°C °C

Symbol	Parameter	BTA/BTB 04-					Unit
		200T	400T	600T	700T	800T	
V _{DRM}	Repetitive Peak off-state Voltage (2)	200	400	600	700	800	V

(1) I_G = 50 mA di/dt = 1 A/μs(2) T_j = 110 °C.**THERMAL RESISTANCES**

Symbol	Parameter	Value		Unit
R _{th (j-a)}	Junction to Ambient	60		°C/W
R _{th (j-c)} DC	Junction to Case for DC	8.7		°C/W
R _{th (j-c)} AC	Junction to Case for 360 ° Conduction Angle (F = 50 Hz)	6.5		°C/W

GATE CHARACTERISTICS (maximum values)

T-25-13

$$P_{GM} = 40 \text{ W} \quad (t_p = 10 \mu\text{s}) \quad I_{GM} = 4 \text{ A} \quad (t_p = 10 \mu\text{s})$$

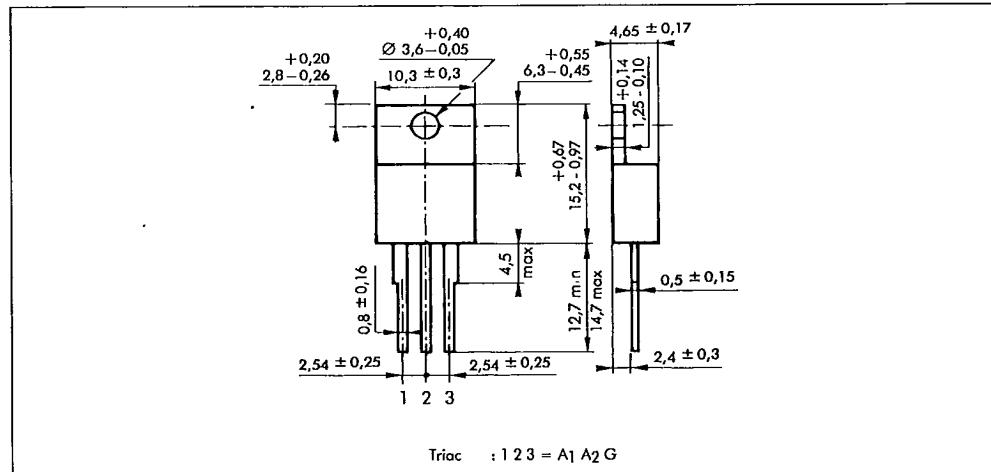
ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit
I _{GT}	$T_J = 25^\circ C$ $V_D = 12 V$ $R_L = 33 \Omega$ Pulse Duration > 20 μs			I-II-III-IV			5	mA
V _{GT}	$T_J = 25^\circ C$ $V_D = 12 V$ $R_L = 33 \Omega$ Pulse Duration > 20 μs			I-II-III-IV			1.5	V
V _{GD}	$T_J = 110^\circ C$ $V_D = V_{DRM}$ $R_L = 3.3 k\Omega$			I-II-III-IV	0.2			V
I _{H*}	$T_J = 25^\circ C$ $I_T = 100 mA$ Gate Open						15	mA
I _L	$T_J = 25^\circ C$ $V_D = 12 V$ $I_G = 10 mA$ Pulse Duration > 20 μs			I-III-IV		15		mA
				II		30		mA
V _{TM*}	$T_J = 25^\circ C$ $I_{TM} = 5.5 A$ $t_p = 10 ms$						1.65	V
I _{DRM*}	V _{DRM} Specified		$T_J = 25^\circ C$				0.01	mA
			$T_J = 110^\circ C$				0.75	mA
dV/dt*	$T_J = 110^\circ C$ Gate Open Linear Slope up to $V_D = 67 \% V_{DRM}$					10	.	V/ μs
(dV/dt) _c *	$T_C = 75^\circ C$ $V_D = V_{DRM}$ $I_T = 5.5 A$ $(dV/dt)_c = 1.8 A/ms$					1		V/ μs
t _{gt}	$T_J = 25^\circ C$ $V_D = V_{DRM}$ $I_T = 5.5 A$ $I_G = 20 mA$ $dI_g/dt = 0.25 A/\mu s$			I-II-III-IV		2		μs

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

PACKAGE MECHANICAL DATA

TO 220 AB Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g.

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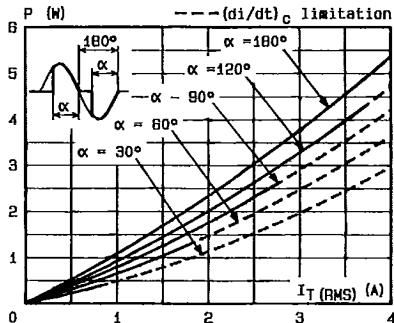
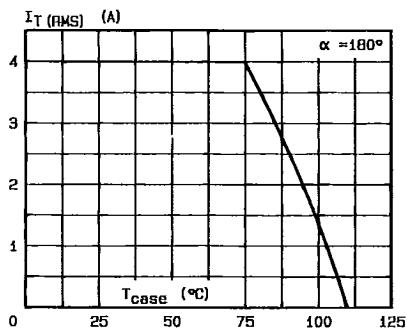
Fig.1 - Maximum mean power dissipation versus RMS on-state current ($f = 60$ Hz).

Fig.3 - RMS on-state current versus case temperature.

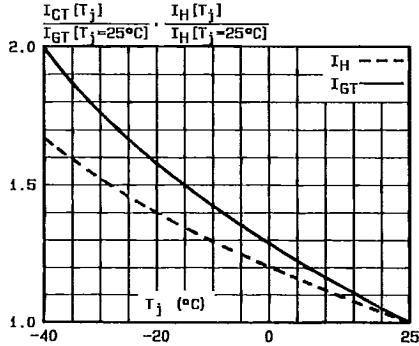


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

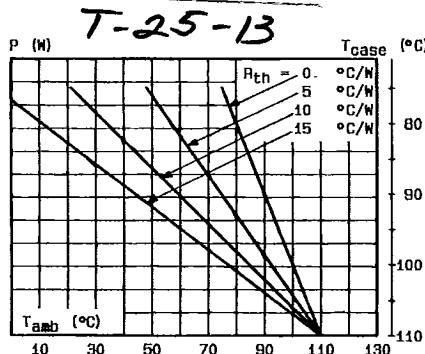
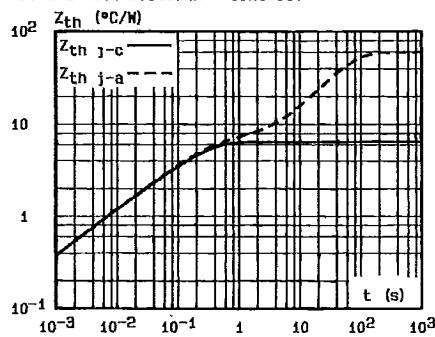
Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

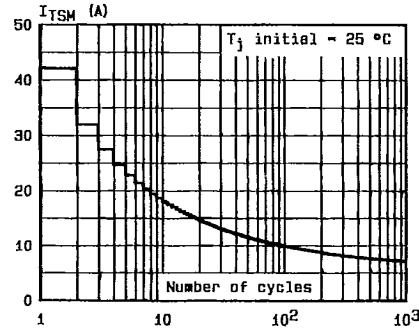


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

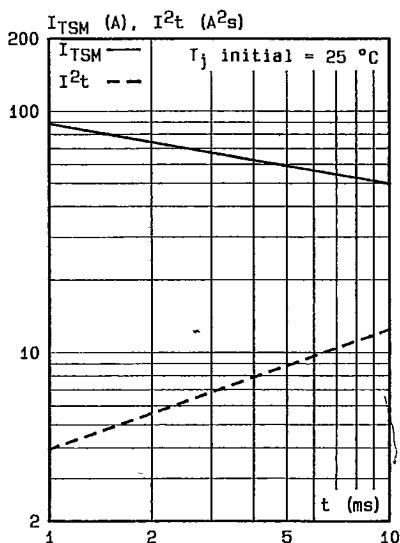


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

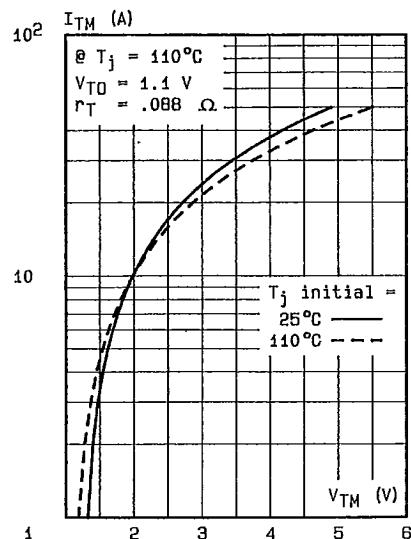


Fig.8 - On-state characteristics (maximum values).